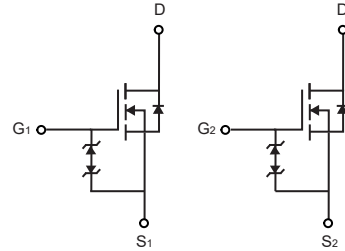


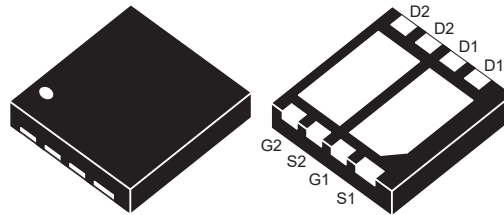
## N-Channel Enhancement Mode Field Effect Transistor

### FEATURES

- 20V, 36A,  $R_{DS(ON)} = 9m\Omega @V_{GS} = 4.5V$ .  
 $R_{DS(ON)} = 12m\Omega @V_{GS} = 2.5V$ .  
 $R_{DS(ON)} = 16m\Omega @V_{GS} = 1.8V$ .
- Super High dense cell design for extremely low  $R_{DS(ON)}$ .
- High power and current handing capability.
- RoHS compliant.
- ESD Protected: 2000 V.



\*Typical value by design



DFN3\*3

### ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ C$ unless otherwise noted

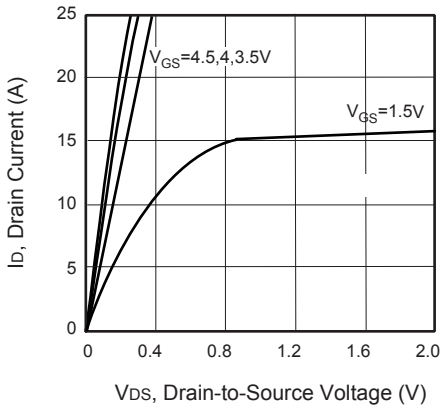
Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	V
Drain Current-Continuous	$I_D @ R_{\theta Jc}$	36	A
	$I_D @ R_{\theta JA}$	14	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM} @ R_{\theta Jc}$	144	A
	$I_{DM} @ R_{\theta JA}$	56	A
Maximum Power Dissipation	$P_D$	17.8	W
Operating and Store Temperature Range	$T_J, T_{stg}$	-55 to 150	$^\circ C$

### Thermal Characteristics

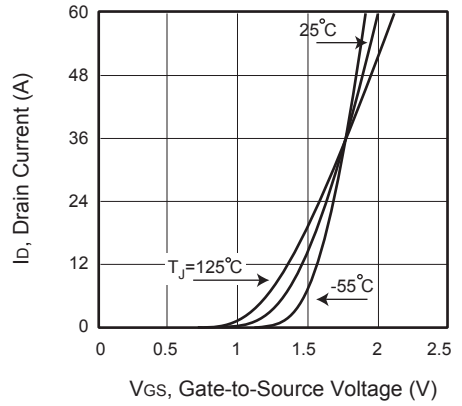
Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case <sup>b</sup>	$R_{\theta Jc}$	7	$^\circ C/W$
Thermal Resistance, Junction-to-Ambient <sup>b</sup>	$R_{\theta JA}$	50	$^\circ C/W$

## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

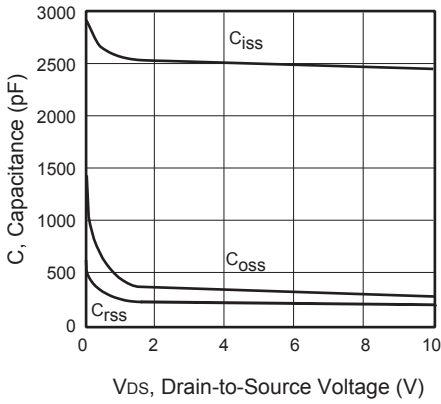
Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	20			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 20V, V_{GS} = 0V$			1	$\mu A$
Gate Body Leakage Current, Forward	$I_{GSSF}$	$V_{GS} = 8V, V_{DS} = 0V$			10	$\mu A$
Gate Body Leakage Current, Reverse	$I_{GSSR}$	$V_{GS} = -8V, V_{DS} = 0V$			-10	$\mu A$
<b>On Characteristics<sup>b</sup></b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS} = V_{DS}, I_D = 250\mu A$	0.35		1	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 4.5V, I_D = 3A$		7	9	$m\Omega$
		$V_{GS} = 2.5V, I_D = 3A$		9	12	$m\Omega$
		$V_{GS} = 1.8V, I_D = 3A$		11	16	$m\Omega$
<b>Dynamic Characteristics<sup>c</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 10V, V_{GS} = 0V, f = 1.0\text{ MHz}$		2495		pF
Output Capacitance	$C_{oss}$			275		pF
Reverse Transfer Capacitance	$C_{rss}$			220		pF
<b>Switching Characteristics<sup>c</sup></b>						
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 16V, I_D = 6A, V_{GS} = 4.5V, R_{GEN} = 6\Omega$		28		ns
Turn-On Rise Time	$t_r$			16		ns
Turn-Off Delay Time	$t_{d(off)}$			80		ns
Turn-Off Fall Time	$t_f$			15		ns
Total Gate Charge	$Q_g$	$V_{DS} = 16V, I_D = 12A, V_{GS} = 4.5V$		24		nC
Gate-Source Charge	$Q_{gs}$			4		nC
Gate-Drain Charge	$Q_{gd}$			5		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current	$I_S$				14	A
Drain-Source Diode Forward Voltage <sup>b</sup>	$V_{SD}$	$V_{GS} = 0V, I_S = 14A$			1.2	V
<b>Notes :</b> □ a.Repetitive Rating : Pulse width limited by maximum junction temperature b.Pulse Test : Pulse Width $\leq 300\mu s$ , Duty Cycle $\leq 2\%$ . □ c.Guaranteed by design, not subject to production testing. □						



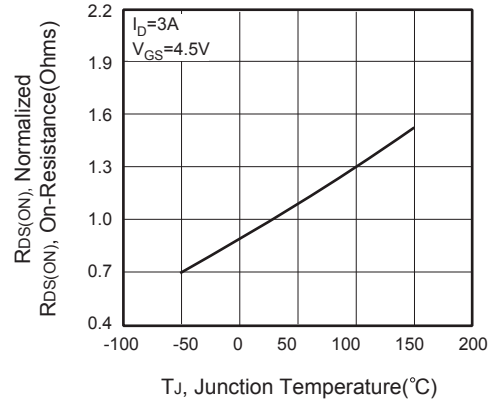
**Figure 1. Output Characteristics**



**Figure 2. Transfer Characteristics**



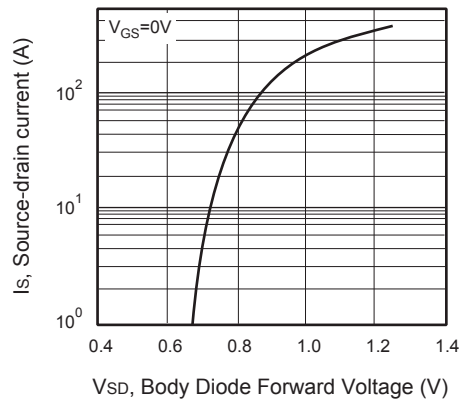
**Figure 3. Capacitance**



**Figure 4. On-Resistance Variation with Temperature**



**Figure 5. Gate Threshold Variation with Temperature**



**Figure 6. Body Diode Forward Voltage Variation with Source Current**

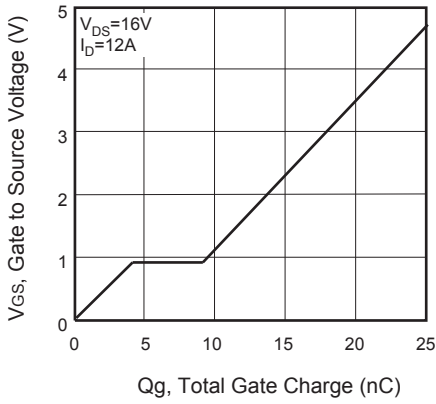


Figure 7. Gate Charge

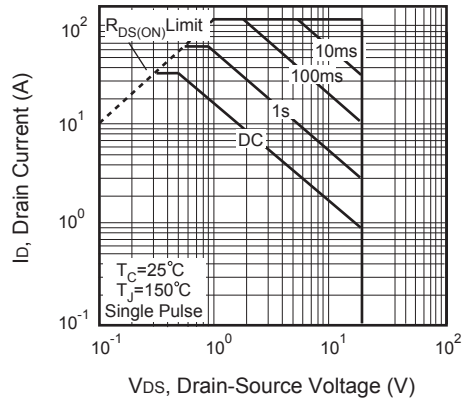


Figure 8. Maximum Safe Operating Area

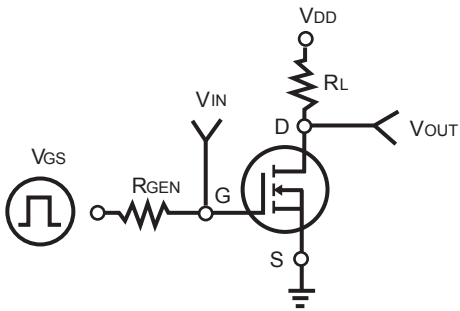


Figure 9. Switching Test Circuit



Figure 10. Switching Waveforms

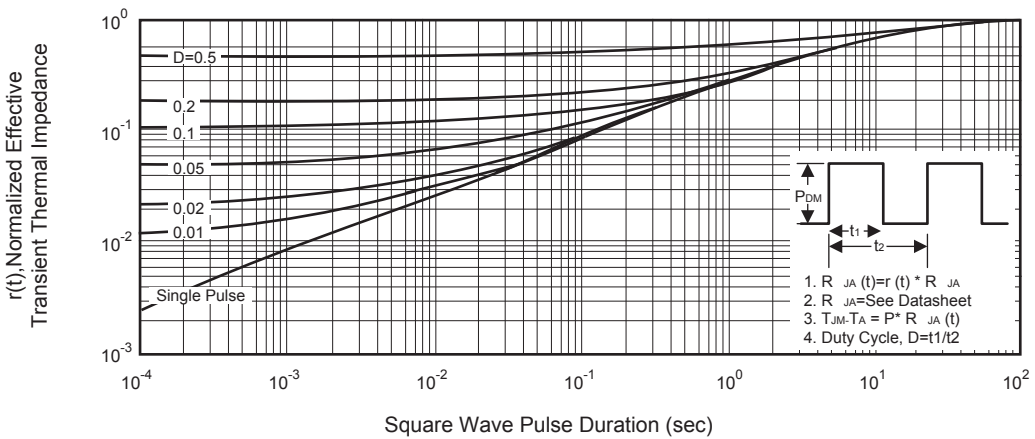


Figure 10. Normalized Thermal Transient Impedance Curve